

ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL		UNITS
Drain-source Volt.(1)	VDSS	400	Vdc
Drain-Gate Voltage (R _{GS} =1.0M Ω) (1)	VDGR	400	Vdc
Gate-Source Voltage Continuous	VGS	± 20	Vdc
Drain Current Continuous (T _c = 25°C)	ID	15	Adc
Drain Current Pulsed(3)	IDM	60	A
Total Power Dissipation	PD	150	W
Power Dissipation Derating > 25°C		1.2	W/°C
Operating & Storage Temp.	TJ/Tsig	-55 TO +150	°C
Thermal Resistance	RthJc	0.8	°C/W
Max. Lead temperature	TL	300	°C

ELECTRICAL CHARACTERISTICS T_c = 25°C (UNLESS OTHERWISE SPECIFIED)

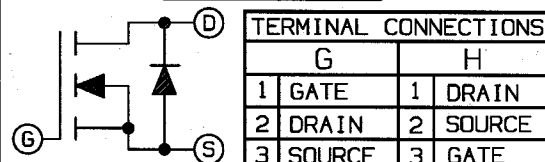
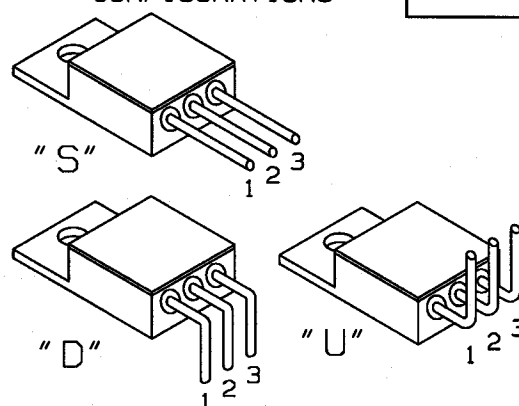
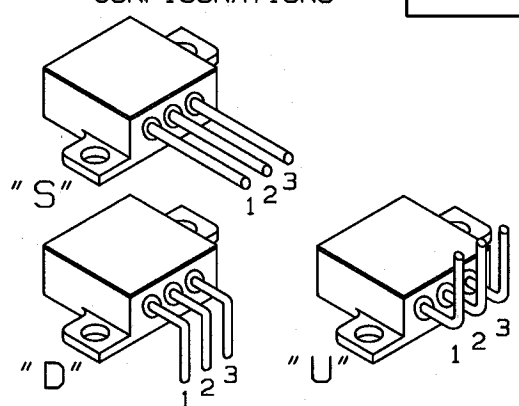
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Drain-source Breakdown Volt.	V(BR)DSS	VGS=0V ID=250 μ A	400	-	-	V
Gate Threshold Voltage	VGS(TH)	VDS=VGS ID=250 μ A	2.0	-	4.0	V
Gate Source Leakage	IGSS	VGS= ± 20 V	-	-	100	nA
Zero Gate Voltage Drain Current	IDSS	VDS=MAX. RATING VGS=0	-	-	250	μ A
		VDS=0.8 MAX. RATING VGS=0 TJ=125°C	-	-	1000	μ A
Static Drain-Source On-State Resistance(1)	RDS(ON)	VGS=10 V ID=8.0A	-	-	0.30	Ω
Forward Trans-Conductance (2)	gfs	VDS $\geq$ 50 V IDS=8.0A	8.0	-	-	S(V)
Input Capacitance	CISS		-	2000	-	pF
Output Capacitance	COSS	VGS=0V VDS=25 V f=1.0 MHz	-	400	-	pF
Reverse Transfer Capacitance	CRSS		-	100	-	pF
Turn-On Delay	td(on)	VDD=180V RG=6.2 Ω ID=8.0A RD=13 Ω	-	-	35	ns
Rise Time	tr	(MOSFET switching times are essentially independent of operating temp.)	-	-	65	ns
Turn-Off Delay	td(off)		-	-	150	ns
Fall Time	tf		-	-	75	ns
Total Gate Charge (Gate-Source Plus Gate-Drain)	Qg	VGS=10V, ID=15A VDS=0.8 MAX. RATING	52	-	110	nC
Gate-Source Charge	Qgs	(Gate charge is essentially independent of the operating temperature)	5.3	-	18	nC
Gate-Drain ("Miller") Charge	Qgd		25	-	65	nC

SOURCE-DRAIN DIODE RATINGS & CHARACT. T_c = 25°C (UNLESS OTHERWISE SPECIFIED)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Continuous Source Current (Body Diode)	IS	Modified MOSFET symbol showing the integral reverse P-N junction rectifier (See schematic)	-	-	15	A
Pulse Source Current (Body Diode) (1)	ISM		-	-	60	A
Diode Forward Voltage (2)	VSD	IF=15A, VGS=0V Tc=+25°C	-	-	1.6	V
Reverse Recovery Time	trr	Tc=+25° C IF=15A	-	-	1300	ns
Reverse Recovery Charge	Qrr	di/dt=100A/ μ S	-	6.6	-	μ C

400V, 15A, 0.30 Ω
SDF350 JAA
SDF350 JAB
FEATURES

- RUGGED PACKAGE
- HI-REL CONSTRUCTION
- CERAMIC EYELETS
- LEAD BENDING OPTIONS
- COPPER CORED 52 ALLOY PINS
- LOW IR LOSSES
- LOW THERMAL RESISTANCE
- OPTIONAL MIL-S-19500 SCREENING

SCHEMATIC

STANDARD BEND CONFIGURATIONS

(CUSTOM BEND OPTIONS AVAILABLE)
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(1) TJ = 25°C to 150°C.
 (2) Pulse test: Pulse Width <300 μ S, Duty Cycle <2%.
 (3) Repetitive Rating: Pulse Width limited By Max. junction Temperature.